2020-2-27 Rev.2.0

RD Number: RD091

TOSHIBA

RD Title: TB62269FTAG Evaluation Circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	OSCM	1	Check terminal	-	_	Logic pin		
2	OUT_A+	1	Check terminal	-	_	Logic pin		
3	OUT_A-	1	Check terminal	_	_	Logic pin		
4	OUT_B+	1	Check terminal	_	_	Logic pin		
5	OUT_B-	1	Check terminal	-	_	Logic pin		
6	VCC	1	Check terminal	_	_	Logic pin		
7	VM	1	Check terminal	_	_	Logic pin		
8	VREF	1	Check terminal	_	_	Logic pin		
9	CW_CCW	1	Check terminal	_	_	Logic pin		
10	MO	1	Check terminal	_	_	Logic pin		
11	GND(7端子)	7	Check terminal	_	_	Logic pin		
12	D_MODE0	1	Check terminal	_	_	Logic pin		
13	D_MODE1	1	Check terminal	_	_	Logic pin		
14	D_MODE2	1	Check terminal	_	_	Logic pin		
15	CLK	1	Check terminal	_	_	Logic pin		
16	ENABLE	1	Check terminal	_	_	Logic pin		
17	RESET	1	Check terminal	_	_	Logic pin		
18	LO	1	Check terminal	_	_	Logic pin		
19	VDD	1	Check terminal	_	_	Logic pin		
20	C_OSCM	1	270pF 1000V	_	_	Chip capacitor		
21	C_VCC	1	0.1μF 100V	_	_	Chip capacitor		
22	C_VDD	1	100μF 25V	_	_	Electrolytic capacitor		
23	C_VM1	1	100μF 50V	_	_	Electrolytic capacitor		
24	C_VM2	1	0.1μF 100V	_	_	Chip capacitor		
25	C_VRF	1	0.1μF 100V	_	_	Chip capacitor		
26	JP_VRF	1	Pin header 2P	_	_	Jumper		

27		1	Jumper socket	_	_	Jumper Short	
28	JP_VCC	1	Pin header 2P	-	_	Jumper	
29		1	Jumper socket	-	_	Jumper Short	
30	R_OSCM	1	5.1kΩ 0.25W	-	_	Chip resistor	
31	R_MO	1	100kΩ 0.25W	-	_	Chip resistor	
32	R_LO	1	100kΩ 0.25W	-	_	Chip resistor	
33	R_RSA	1	0.22Ω 1W	-	_	Chip resistor	
34	R_RSB	1	0.22Ω 1W	-	_	Chip resistor	
35	D_MODE0	1	Pin header 3P	-	_	Jumper	
36		1	Jumper socket	-	_	Jumper Short	
37	CW_CCW	1	Pin header 3P	-	_	Jumper	
38		1	Jumper socket	_	_	Jumper Short	
39	D_MODE1	1	Pin header 3P	-	_	Jumper	
40		1	Jumper socket	-	_	Jumper Short	
41	CON1	1	Connector 4P	_	_	Connector 4P-2.5	
42	C_OAP	0	Not mount	_	_	Chip capacitor	✓
43	C_OAM	0	Not mount	_	_	Chip capacitor	✓
44	C_OBM	0	Not mount	_	_	Chip capacitor	✓
45	C_OBP	0	Not mount	_	_	Chip capacitor	✓
46	RSA	0	Not mount	_	_	Logic pin	✓
47	RSB	0	Not mount	_	_	Logic pin	✓
48	R_VRF1	0	Not mount	_	_		✓
49	R_VRF2	0	Not mount	_	_		✓
50	R_VRF1	2	Socket pin	_	_	Socket pin	
51	R_VRF2	2	Socket pin	_	_	Socket pin	
52	SW1	0	Pin header 3P	_	_	Jumper	✓
53		0	Jumper socket	_	_	Jumper Short	✓
54	SW4	0	Pin header 3P	_	_	Jumper	✓
55		0	Jumper socket	_	_	Jumper Short	✓
56	D_MODE2	1	Pin header 3P	_	_	Jumper	
57		1	Jumper socket	_	_	Jumper Short	
58	SW7	0	Pin header 3P	_	_	Jumper	✓
59		0	Jumper socket	-	_	Jumper Short	✓
60	ENABLE	1	Pin header 3P	_	_	Jumper	

61		1	Jumper socket	_	_	Jumper Short		
62	RESET	1	Pin header 3P	_	_	Jumper		
63		1	Jumper socket	_	_	Jumper Short		
64	IC1	1	TB62269FTAG	TB62269FTAG	TOSHIBA	Motor driver IC	QFN32	

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